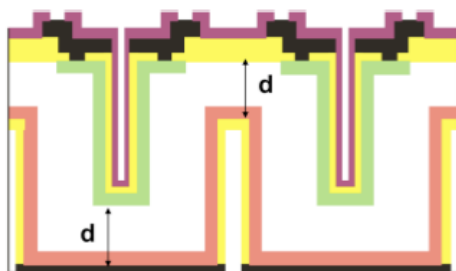


Initial characterization of 3D-DDTC detectors with ATLAS Pixel readout chip

B. Di Girolamo, D. Dobos, A. La Rosa, H. Pernegger
(CERN – PH)

On bench measurement

- Recently started to do measurements on 3D-DDTC Silicon Sensor:
 - Leakage currents
 - Threshold scan (threshold and noise measurements)
 - Noise vs bias voltage
 - Calibration and first source test with 241Am source



M. Boscardin
(FBK-irst)
G.F. Dalla Betta
(UniTN&INFN-TN)

DDTC on p-type substrate

Structure with 2,3 and 4 electrodes per pad

Sensor type	Distance (μm)
2E	103
3E	71
4E	56

Thickness 220 μm

Column overlap $\sim 100 \mu\text{m}$

Depletion voltage $\sim 11\text{V}$

Detector	Measurements
2EM2	$I_{Leakage}$, Threshold scan; Noise vs HV; source
2EM4	$I_{Leakage}$
2EM6	$I_{Leakage}$; Threshold scan; Noise vs HV; source
3EM1	$I_{Leakage}$
3EM5	$I_{Leakage}$; Threshold scan; Noise vs HV; source
3EM7	$I_{Leakage}$; Threshold scan; Noise vs HV; source
4EM3	$I_{Leakage}$; Threshold scan; Noise vs HV; source
4EM8	$I_{Leakage}$; Threshold scan; Noise vs HV; source
4EM9	$I_{Leakage}$; Threshold scan; Noise vs HV; source

Contribution to measurements: N. Darbo, G. Gariano, A. Rovani, E. Riuscino / INFN-Genova

Pixel Lab at Bat. 161

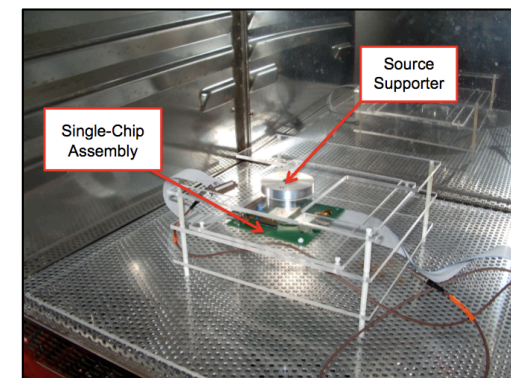
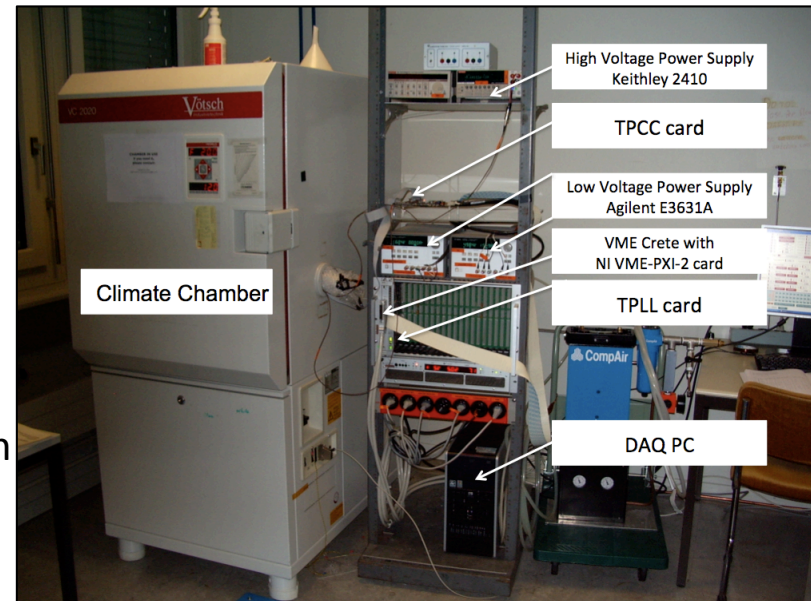
The Lab is operated as semi-clean room with safety precaution for cleanliness and radiation zone

PIXEL TEST STATION (based on Turbo DAQ system)

✓ with SOURCE:

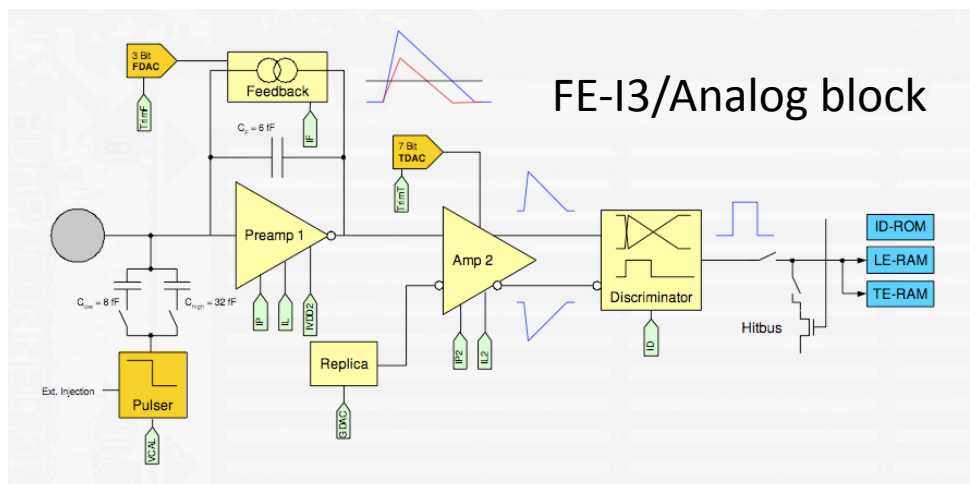
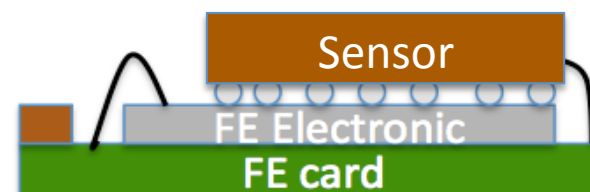
- Climate chamber (-25÷100 °C) + Liquid cooling
- Source : a) Am 60KeV self triggered for calibration
b) Sr90 trigger independently triggered by scintillator (working in progress)

✓ for calibration and front-end electronic test
- mobile system, on-loan from INFN/Genova

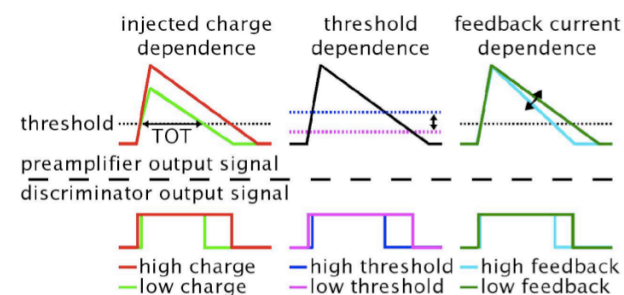


Single-chip assembly

3D-DDTC sensors are bump bonded on ATLAS FE-I3 readout chip.



Preamplifier and discriminator shape



Overall chip architecture:

- Standard 0.25um CMOS technology
- 2880 readout cells of 50um x 400um
- 18x160 matrix

Each readout cell:

Analog block where the sensor charge is amplified and compared to a programmable threshold by a discriminator;

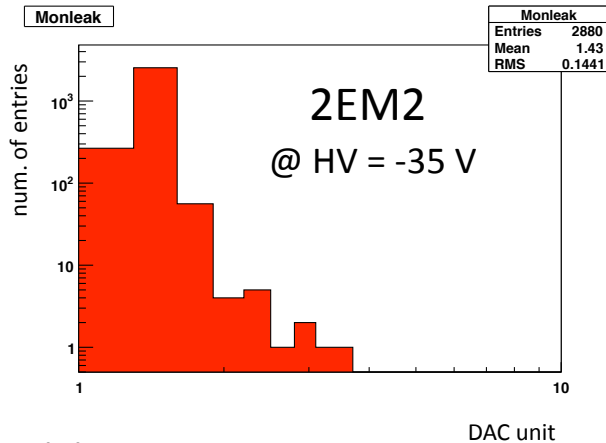
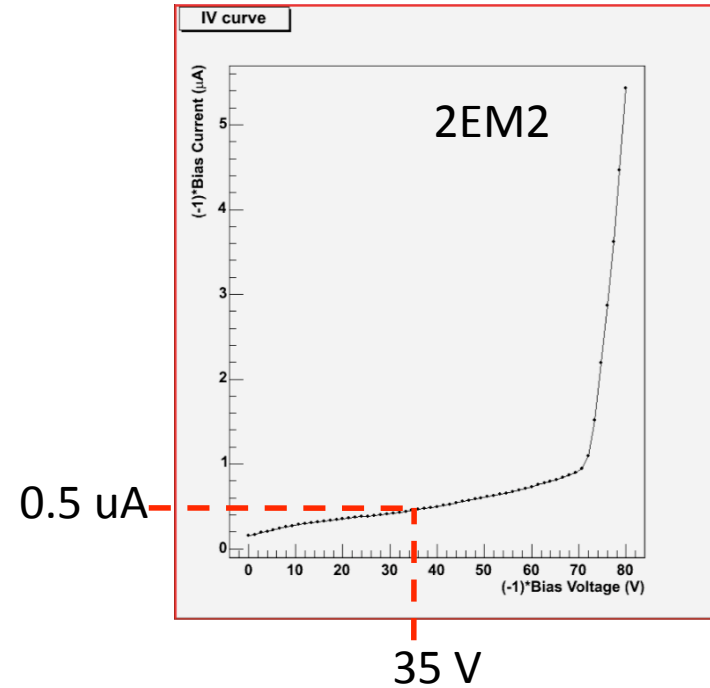
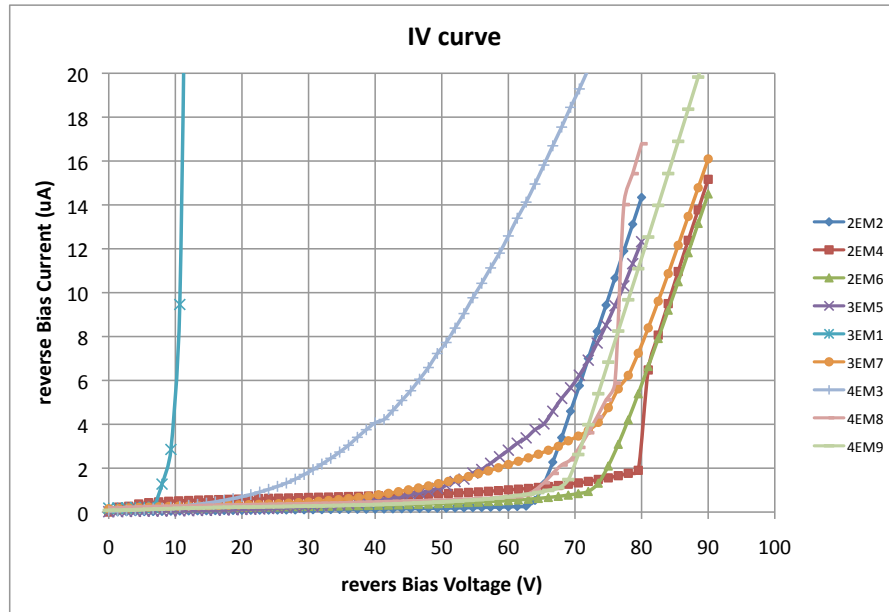
Digital readout part transfers the hit pixel address, a hit time stamp and a digitized amplitude information, the ToT to buffers at the chip periphery.

Time over Threshold (length of discriminator signal) depends on:

- deposited charge
- discriminator threshold
- feedback current

Information of the ToT (in unit of 25 ns) is read out together with the hit information

Leakage currents



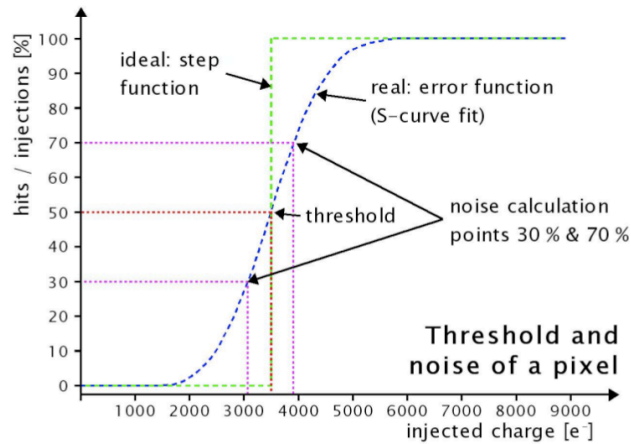
Monleak \rightarrow leakage current for each pixel in DAC unit
(1 DAC = 125pA)

$$\langle I_{\text{leak}} \rangle = 1.43 \text{ DAC unit} \rightarrow \langle I_{\text{leak}} \rangle \sim 179 \text{ pA}$$

$$\text{Per chip} \rightarrow 179 \text{ pA} \times 2880 = 0.52 \text{ } \mu\text{A}$$

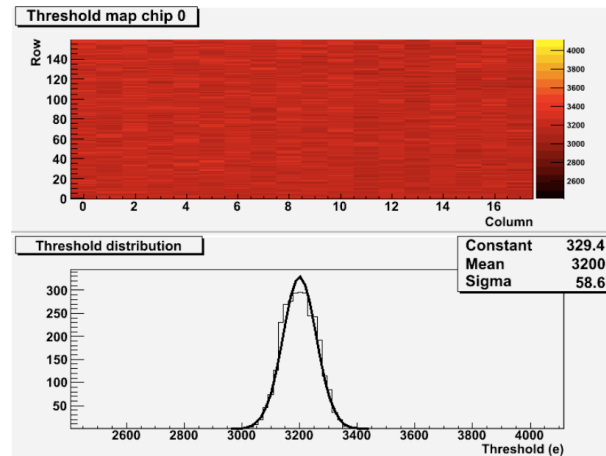
Threshold scan

Performed to measure the threshold and noise of each pixel

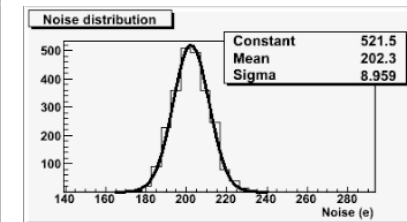


- A voltage pulse is injected into the injection capacitor (eg Clow).
- The input amplifier see a signal of $V_{pulse} \times Clow$.
- 100 digital injection are performed for each pxl and each injected charge value between $0e^-$ and $9000e^-$ in several steps.
- The num. of collected hits for each pxl and each injected charge is recorded.
 - **Measure response (hit/injection).**
- Response fuction: convolution of ideal step function and Gaussian pxl noise distribution → error fuction.
- Fit gives **threshold** and **noise** value.

FE Tuned with Th=3k2e- and 60 ToT @ 20ke-

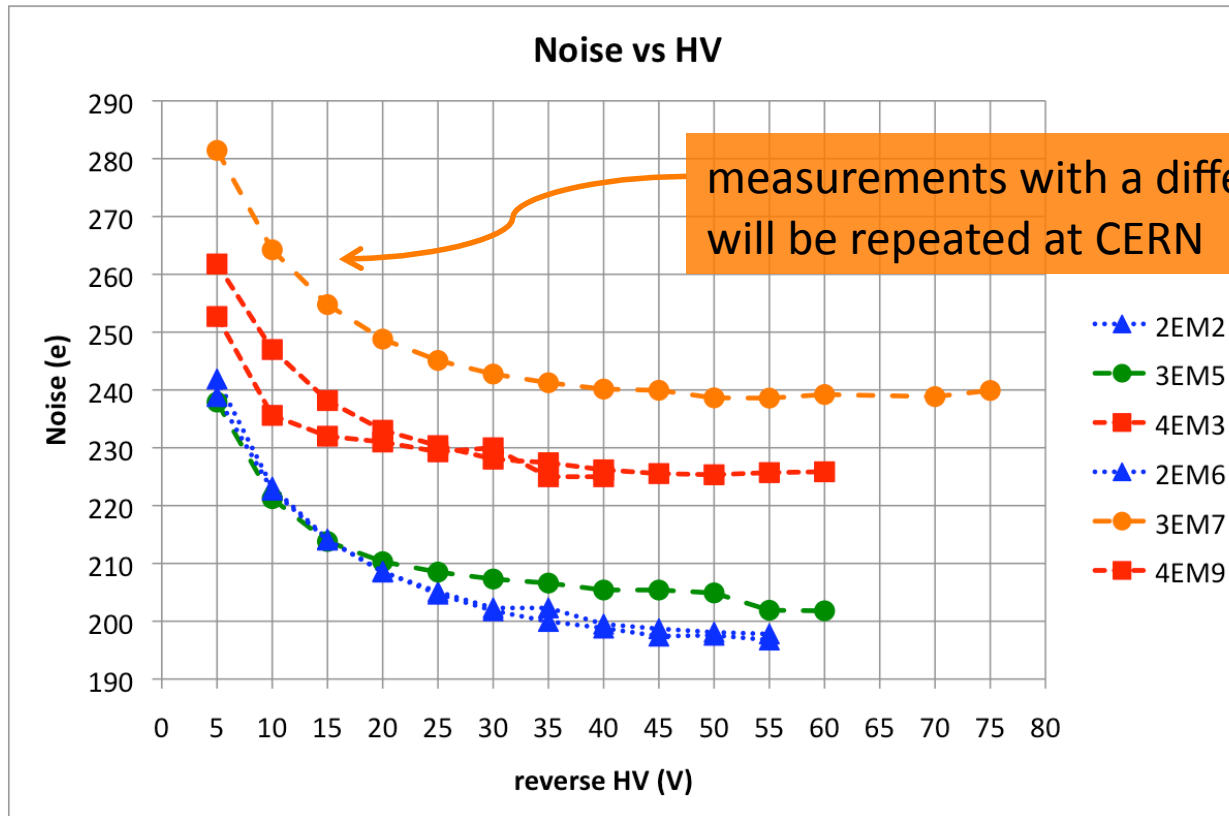


3D-DDTC
2EM2



Detector	$\langle Th \rangle$ (e)	$\sigma(Th)$ (e)	$\langle N \rangle$ (e)	$\sigma(N)$ (e)	HV (V)
3D-2EM2	3200	58.6	202.3	8.96	-35
3D-2EM6	3281	49.57	199.4	9.55	-35
3D-3EM5	3318	42.02	206.6	8.29	-35
3D-3EM7	3302	53.37	244.9	9.80	-35
3D-4EM3	3284	41.27	229.8	9.87	-25
3D-4EM8	3314	70.11	232.7	12.32	-35
3D-4EM9	3294	56.08	225.9	10.65	-35
3D-3EG	3241	64.48	291.7	13.03	-35
ATLASnn	3259	42.96	125.9	16.23	-150

Noise vs bias voltage



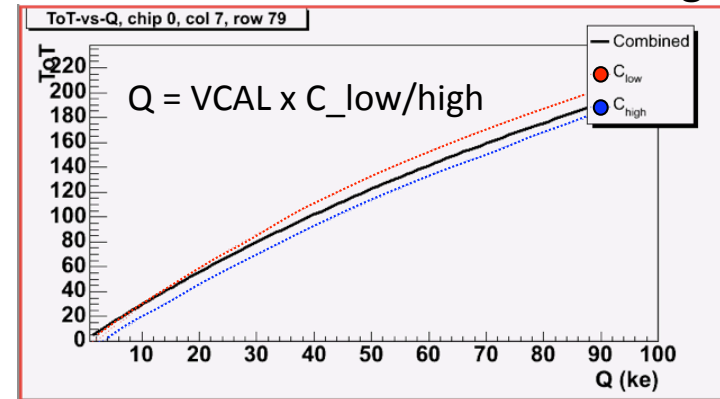
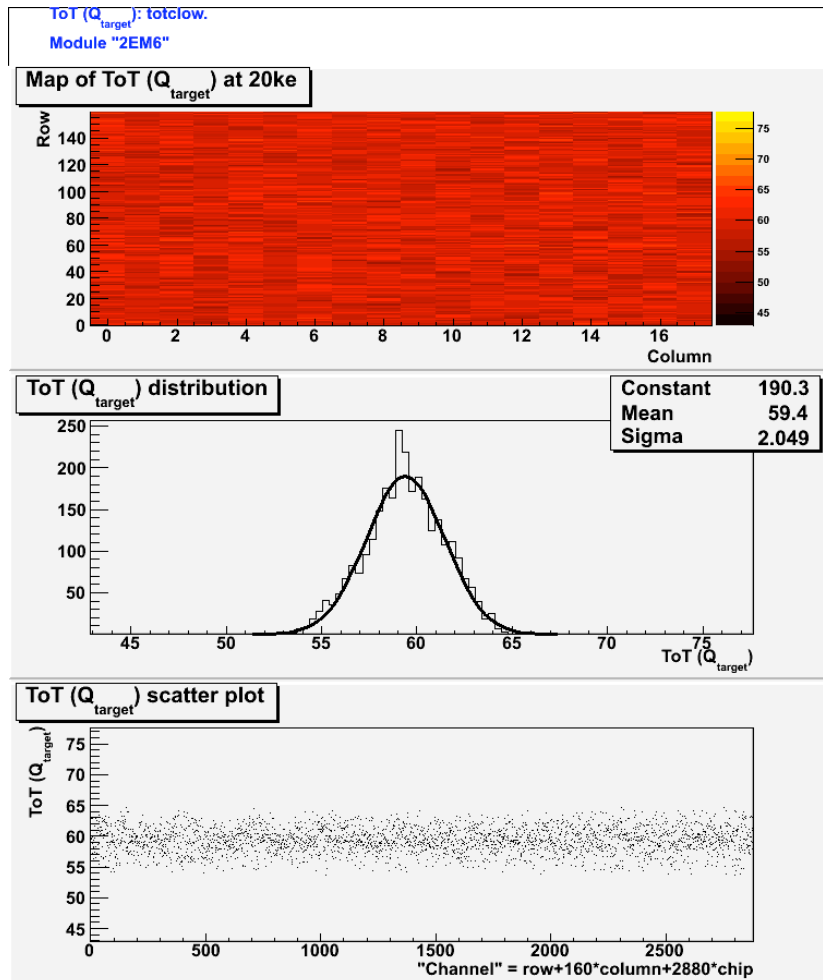
- ▲ 2 electrodes per pixel
- 3 electrodes per pixel
- 4 electrodes per pixel

Measurements at CERN setup (climate chamber) 20 °C and relative humidity of 12%.

Self-ToT calibration

Performed to determine the charge dependence of the ToT values for each pixel
Procedure and algorithms described in ATLAS Project Document No: ATL-IP-QP-0144

It injects a different charges above the threshold and measures the average ToT



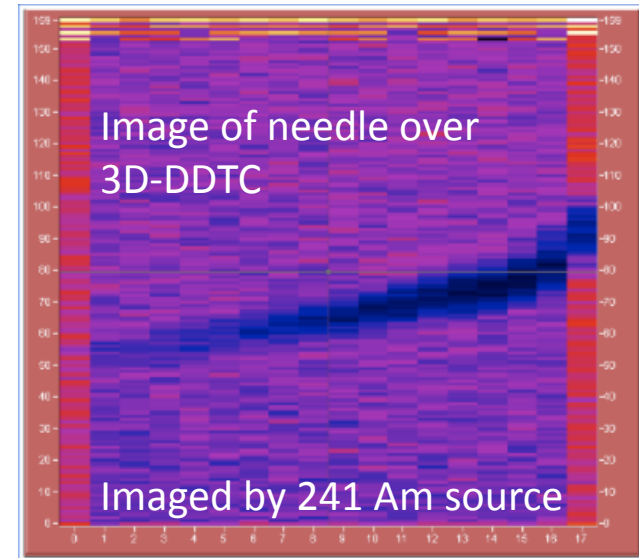
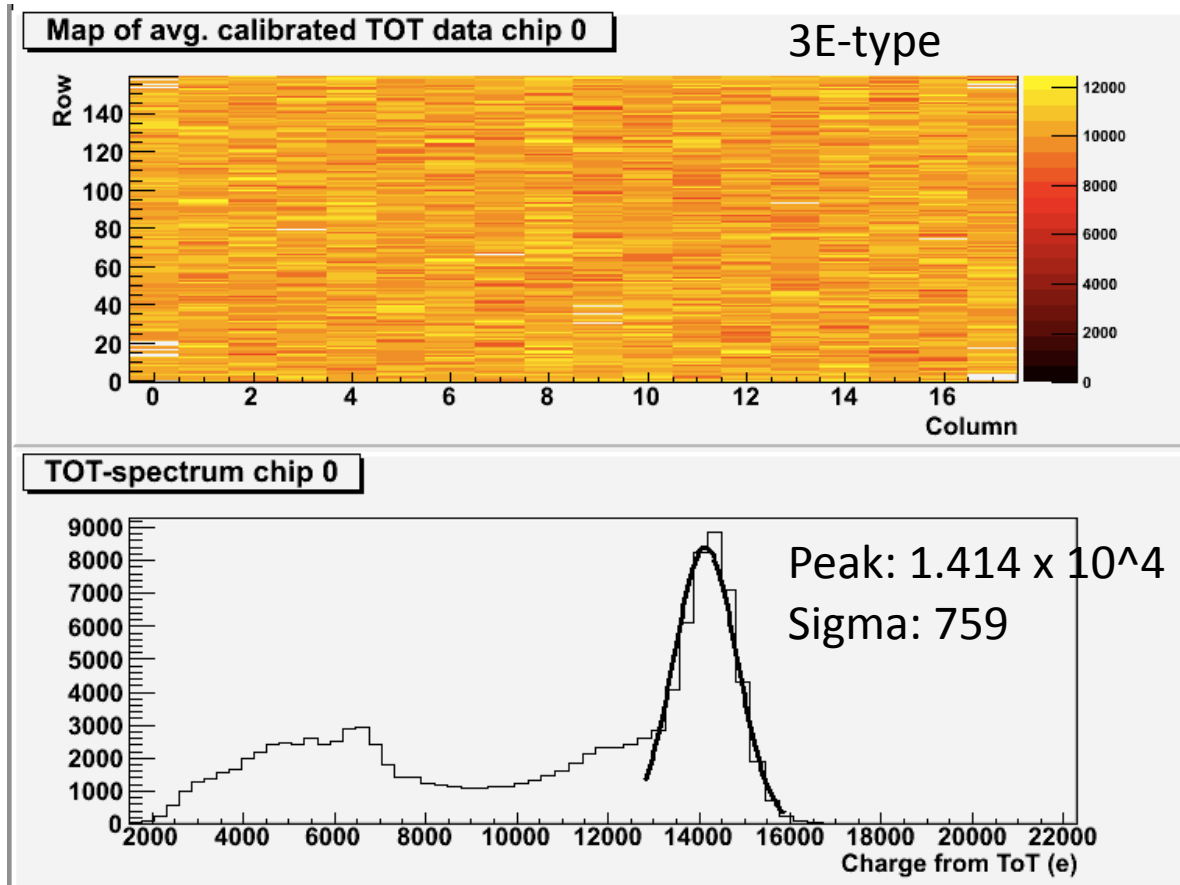
ToT tuned with 60 ToT @ 20ke-

Detector	<ToT>	σ (ToT)	HV (V)
3D-2EM2	61.99	1.564	-35
3D-2EM6	59.4	2.049	-35
3D-3EM5	61.9	1.833	-35
3D-3EM7	59.07	1.946	-35
3D-4EM3	61.8	1.777	-25
3D-4EM8	59	2.177	-35
3D-4EM9	59.4	2.049	-35
3D-3EG	60.74	2.703	-35

SAME SETUP

Source test

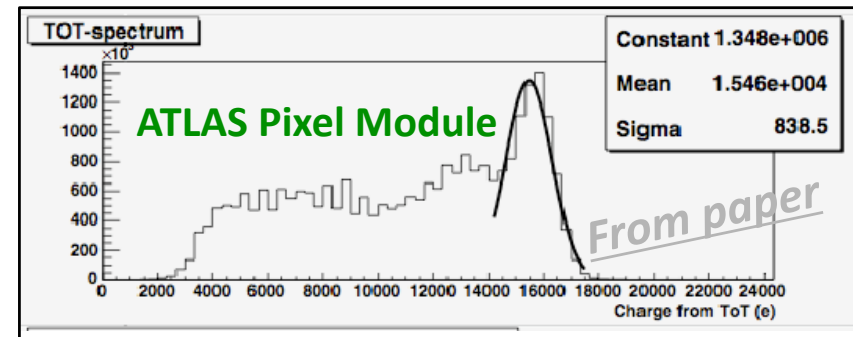
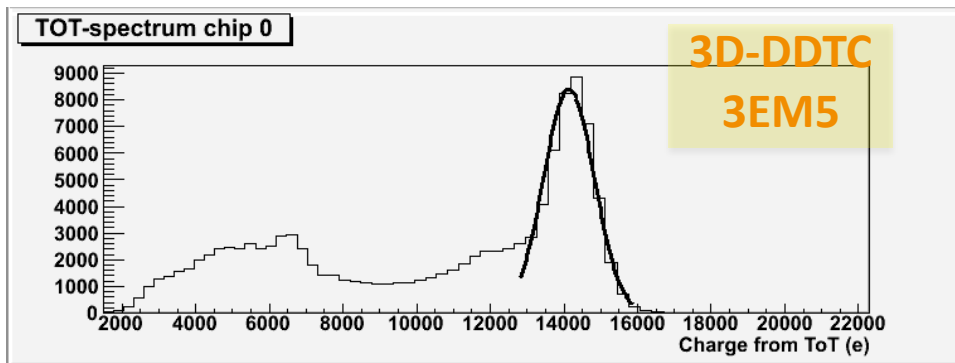
Preliminary measurement with ^{241}Am



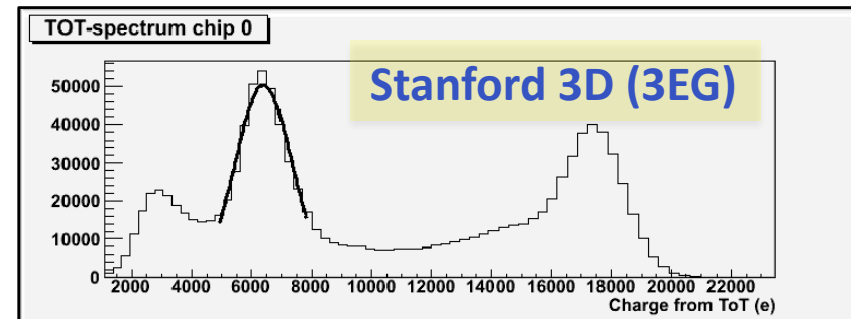
Source test

Preliminary measurement with ^{241}Am source in comparison with **ATLAS Pixel full module** and **Stanford 3D** sensor

Spectrum as a sum over all pixel without any clustering



Detector	<Peak> ($10^4 e$)	Sigma (e)
3D-2EM2	1.411	695.3
3D-2EM6	1.401	673.6
3D-3EM5	1.414	686.2
3D-3EM7	1.537	778.4
3D-4EM3	1.406	759
3D-4EM8	1.383	775.2
3D-4EM9	1.415	760.0



SAME SETUP

Not 26.3 keV (7.3 Ke-) and 13.9 keV (3.8ke-) (?)
To be investigated !!!!!

Outlook

- We've just started to look at 3D-DDTC sensors too early for a summary !
- Part of the activities has been already presented in several conference and workshops: RESMDD08; IEEE; ATUW-Nikhef; RD50 Workshop; INFN Meeting: Atlas and CMS Upgrade for S-LHC.
- The performance of the 3D-DDTC have been studied by measuring:
 - Leakage currents
 - Threshold scan (threshold and noise measurements)
 - Noise versus bias voltage
 - Calibration and first source test with ^{241}Am source ★★★★★
(A note on this study is going to be prepared)
- 9 detectors have been tested: one of them (3EM1) has showed problem in IV scan (breakdown $\sim -10\text{V}$), while one (2EM4) has presented problems in the FE calibration.
- Many thanks to M. Boscardin (FBK-irst), G.F. Dalla Betta (UniTN&INFN-Trento) and N. Darbo, G. Gariano, A. Rovani, E.Ruscino (INFN- Genova) for their kind cooperation in the detector understanding and measurements.

Outlook

- Present/Future interest:
 - Study of detector behavior in terms of noise and threshold:
 - Using the same setups
 - Before and after irradiation
 - Warm and cold measurements
 - Strongly support testbeam activity:
 - Device preparation and characterization before testbeam
 - Data taking
 - Data analysis